



SIES 2024

23-25 October 2024, Chengdu, China

14th IEEE International Symposium on Industrial Embedded Systems

2024 IEEE 14th International Symposium on Industrial Embedded Systems (SIES 2024) will be held from 23 to 25 October in Chengdu, China. SIES 2024 is co-sponsored by IEEE and University of Electronic Science and Technology of China, China.

The SIES series was hosted by University of Nice Sophia Antipolis, France (2006); Uninova, Portugal (2007); LIRMM/CNRS, France (2008); Ecole Polytechnique Fédérale de Lausanne, Switzerland (2009); University of Trento, Italy (2010); Mälardalen University, Sweden (2011); Karlsruhe Institute of Technology, Germany (2012); Polytechnic Institute of Porto, Portugal (2013); Scuola Superiore S. Anna, Italy (2014); Siegen University, Germany (2015); AGH UST, Poland (2016), and France (2017), Graz University of Technology, Austria (2018).

The aim of the symposium is to bring together researchers and practitioners from industry and academia. SIES provides a platform to report on recent developments, deployments, technology trends and research results, as well as to discuss and start initiatives related to embedded systems and their applications in a variety of industrial environments.

Topics

- Embedded Systems
 - System-on-Chip and Network-on-Chip Design & Testing
 - Networked Embedded Systems and Edge Computing
 - Embedded Applications
- Detailed topics: <https://iee-sies.org/cfp.html>

Conference Award

- Outstanding Paper Award
- Best Reviewer Award
- Best Paper Award
- Best WIP Paper Award
- Best Presentation Award

Proceedings



Accepted and registered full papers will be published by IEEE Conference Proceedings, and submitted for Ei Compindex & Scopus index.

Submission of Papers

- **Long Paper** (up to 8 double-column pages)
Each paper should be at least with 4 pages by following the template so that it can meet the standard of the press.
- **WIP Papers** (up to 4 double-column pages)
Ongoing research projects, pilot programs, or the like, can be presented at SIES under the Work in Progress (WIP) category. Preliminary results are expected to be reported.
- **Poster Presentation**
If you only want to share and discuss your latest research with others at the conference, you can submit an abstract for poster presentation.
- **Submission Link:** <https://easychair.org/my/conference?conf=sies2024>
- **Template:**
Word: <https://iee-sies.org/downloads/conference-template-letter.docx>
Latex: <https://iee-sies.org/downloads/conference-latex-template.zip>

Important Dates

Submission deadline: June 11th AoE
 Notification: July 28th AoE
 Registration: August 20th AoE

Contact US

SIES Secretary: Amy Hu
 E-mail: iee-sies@academic.net

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